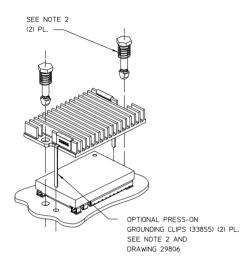
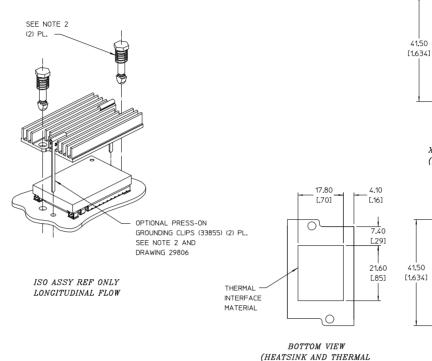
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ISO ASSY REF ONLY X-FLOW



PUSH-PIN FOR VI-CHIP HEATSINK CHART

INTERFACE MATERIAL ONLY)

PUSH-PINS W/ SPRINGS (100/BAG)	COLOR	PCB THK NOMINAL RANGE	PCB THK MINIMUM	PCB THK MAXIMUM
32434	WHITE	1,30 TO 1,75 MM [.051*] TO [.069*]	1,168 MM [.046"]	1.956 MM [.077*]
32435	BLACK	1.78 TO 2.64 MM [.070"] TO [.104"]	1.600 MM [.063"]	2.921 MM [.115*]
32436	BLUE	2.67 TO 3.35 MM [.105"] TO [.132"]	2.388 MM [.094*]	3.706 MM [.146*]
32437	GRAY	3.38 TO 3.96 MM [.133"] TO [.156"]	3.048 MM [.120*]	4.369 MM [.172*]

REV.	DESCRIPTION	DATE	APVD
1	RELEASED PER E053460 LEK	12/08/05	RT
2	REVISED PER E063752 PEI	03/29/06	RT
3	REVISED PER E063923 GCK	5/25/06	RT
4	REVISED PER E071489 JS	07/19/07	REJH
5	REVISED PER E072325 JS	09/25/07	REJH
6	REVISED PER E080727 SA	4/9/08	REJH
7	REVISED PER E100891 GCK	7/8/10	REJH

X-FLOW (XF) (HEAT SINK ONLY SHOWN)

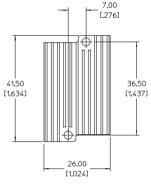
26.00 [1.024]

41.50

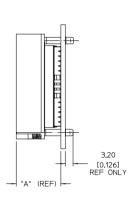
7.00 [.276]

36,50

[1.437]



LONGITUDINAL FLOW (LF) (HEAT SINK ONLY SHOWN)



J-LEAD MOUNT

HEATSINK CHART

HEAT SINK HEIGHT	XF P/N	XF "A" DIM	LF P/N	LF "A" DIM
11MM	34072	17,83/[.702]	34074	17.83/[.702]
6.3MM	34073	13.13/[.517]	34075	13.13/[.517]

DRAWN BY D.CVINAR	7/27/05	_M_VICOR_	
UNLESS OTHERWISE SPECIFIED DHENSONS ARE IM (INO)! TOLERANCES ARE: DOOR - 4025 [400] APRILES XX (DOX) - 4027 [4005]		YIM	
		ASSEMBLY DWG. VIC PUSH PIN HEATSI	NK
THIRD ANGLE PR	OJECTION	SIZE CAGE CODE DWG NO	REV
⊕-∈1		D 67131 30553	7
DO NOT SCALE D	RAWING	SCALE 2:1 SHEET 1	of 1

NOTES:

1. FOR PCB LAYOUT SEE VICOR APPLICATION DRAWING 29806 FOR J-LEAD MOUNT V*I CHIP.

2. PUSH-PIN INSTALLATION:

TO MINIMIZE STRESS IN THE VIC-TO-PCB SOLDER CONNECTIONS, PRESS THE PUSH-PINS THROUGH THE HOLES ON THE HEATSINK AND PRESS THE OPTIONAL GROUNDING CLIPS (33855) ONTO THE HEATSINK FINS PRIOR TO HEATSINK INSTALLATION ON THE VIC.

ALIGN THE GROUNDING CLIPS TO THE PCB. PLACE
THE HEATSINK ASSEMBLY ON THE SURFACE OF THE VIC,
AND PRESS THE PUSH-PINS THROUGH THE HOLES ON THE
PCB. IT IS CHITICAL TO SUPPORT THE UNDERSIDE OF
THE PCB AT EACH HOLE LOCATION TO AVOID FLEXING
THE PCB DURING PUSH-PIN INSTALLATION. SOLDER
GROUNDING TABS TO PCB.

CARE SHOULD BE TAKEN TO AVOID FULLY COMPRESSING THE PUSH-PIN SPRINGS DURING INSTALLATION AS THIS WOULD EXPOSE THE VIC TO FORCES GREATER THAN THE RECOMMENDED LIMIT OF 3 LBF (13,3 N) PER PUSH-PIN.

3. RoHS COMPLIANT PER CST -0001 LATEST REVISION

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